

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Daewoong Suh

Examiner: John B. Vigushin

Serial No.: 10/808,192

Group Art Unit: 2841

Filed: March 24, 2004

Docket: 884.C25US1

Title: SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

Customer Number: 21186

RESPONSE TO RESTRICTION REQUIREMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Restriction Requirement mailed April 11, 2006, Applicant hereby provisionally elects, with traverse, Group I (claims 1-13). **If the restriction is continued**, Applicants will cancel remaining claims 14-22 (with prejudice), and will reserve the right to reintroduce them in one or more divisional applications at a later date.

The Restriction Requirement is traversed on the basis that Restriction Requirements are optional in all cases. MPEP 803. If the search and examination of an entire application can be made without serious burden, the Examiner must examine it on the merits, even though it arguably may include claims to distinct or independent inventions. MPEP 803.

All of the pending claims relate to semiconducting devices, electronic systems and methods that include (i) a motherboard that includes a first contact; (ii) an electronic package that includes a second contact bonded to the first contact; and (iii) an interlayer diffused within the first and second contacts such that the bonded first and second contacts have a higher melting temperature than the interlayer before being diffused into the first and second contacts. The Examiner will be looking for a motherboard, electronic package, first and second contacts and an interlayer as recited in each of claims 1-22. Thus, Applicant respectfully submits that these claims can all be easily searched and examined together.

As part of maintaining the restriction, the Examiner states at page 2 of the Office Action that

"in the instant case, the product as claimed can be made by another and materially different process, such as a process that requires maintaining the interlayer and the first and second contacts within the environment until only 50% or less of the interlayer diffuses in to the first and second contacts, and wherein engaging a first contact on a motherboard with a second contact on an electronic

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package requires only heating without the step of pressing the first contact against the second contact."

Applicant can not see where the statement adequately indicates that claims 1-13 are distinct inventions from claims 14-22. Clarification is respectfully requested.

In addition, Applicant also respectfully fails to see the relevance and accuracy of the statements because each of claims 1-22 recites a motherboard, electronic package, first and second contacts and an interlayer. Applicant further notes that the Examiner will be searching for each of these items without regard to (i) how much of the interlayer is diffused into the first and second contacts; and (ii) whether the first and second contacts are bonded together by pressing and/or heating.

The Examiner is invited to telephone Applicant's attorney Andrew Peret at 262-646-7009 to facilitate prosecution of this application. If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,
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By / Andrew Peret /
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